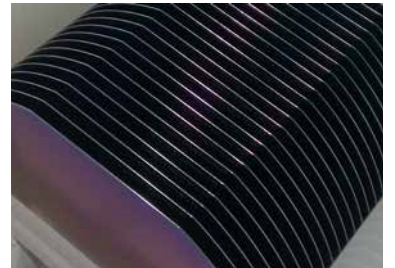
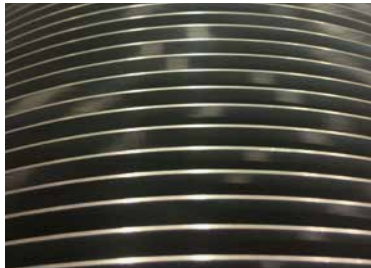
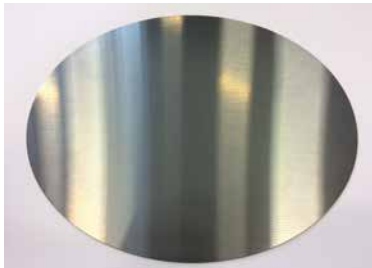


DW 292

MULTI WIRE SAW



WORK PIECE DIMENSIONS:
MAX. Ø 305 MM × 650 MM



12" WAFER AT HIGHEST PRECISION AND THROUGHPUT

- ✓ High wire speed and acceleration
- ✓ Patented Diamond Wire Management System (DWMS)
- ✓ High process automation
- ✓ Sophisticated work piece rocking

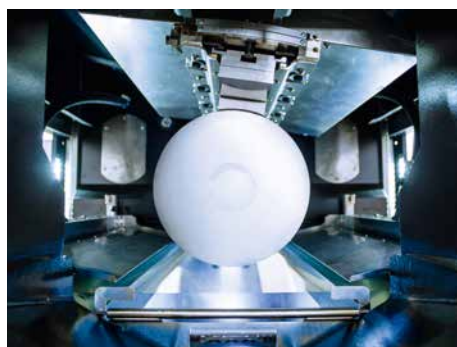
SMART SLICING TECHNOLOGY FOR SEMICONDUCTOR WAFERING

HIGHLIGHTS DW 292

- ✔ Sophisticated work piece rocking for maximum precision
- ✔ High throughput: 35 m/s wire speed, 12 m/s² acceleration
- ✔ DWMS: 60 μm wire capability
- ✔ Shortest wire path: Only <1.9 m on one side, easy wire set-up and constant tension
- ✔ Robust machine: Mineral cast, low temperature dependency, low vibration, low noise
- ✔ HMI: New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- ✔ Option: Automatic cutting fluid exchange
- ✔ Option: MES interface (SECS / GEM)



Long load length for high output



Optimized work piece rocking for higher wafer quality



Easy operation for higher yield

TECHNICAL DATA	DW 292 FEATURES
Web length [mm]	660
Max. work piece dimensions [mm]	Ø 305 × 650
Wire speed [m/sec]	35
Wire acceleration [m/s ²]	12 (<3.5 s)
Min. wire diameter [μm]	60
Max. wire tension [N]	28
Rocking principle	Rocking of work piece
Rocking angle [°]	± 8
Wire guide roller axis distance [mm]	580
Cutting fluid tank [l]	300
Machine dimensions [L × W × H] [mm]	3610 × 1380 × 2860
Machine weight [kg]	9300

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TOGETHER WE WILL FIND A SOLUTION
FOR YOUR REQUIREMENTS

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